

N-channel 25 V 8.65 m Ω logic level MOSFET in LFPAK33 using NextPower Technology

Rev. 3 — 15 June 2012

Product data sheet

1. Product profile

1.1 General description

Logic level enhancement mode N-channel MOSFET in LFPAK33 package. This product is designed and qualified for use in a wide range of industrial, communications and domestic equipment.

1.2 Features and benefits

- Low parasitic inductance and resistance
- Optimised for 4.5V Gate drive utilising NextPower Superjunction technology
- Ultra low QG, QGD, & QOSS for high system efficiencies at low and high loads

1.3 Applications

- DC-to-DC converters
- Load switching

Synchronous buck regulator

1.4 Quick reference data

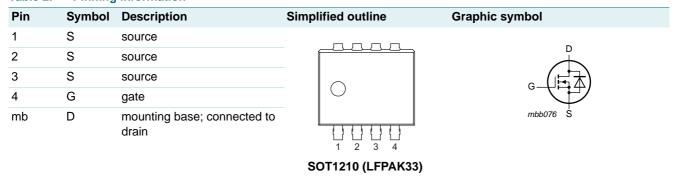
Table 1. Quick reference data

Symbol	Parameter	Conditions	Min	Тур	Max	Unit
V_{DS}	drain-source voltage	$T_j = 25^{\circ}C$	-	-	25	V
I _D	drain current	T_{mb} = 25 °C; V_{GS} = 10 V; see <u>Figure 1</u>	-	-	55	Α
P _{tot}	total power dissipation	T _{mb} = 25 °C; see <u>Figure 2</u>	-	-	45	W
T _j	junction temperature		-55	-	175	°C
Static characte	eristics					
R _{DSon}	drain-source on-state resistance	$V_{GS} = 4.5 \text{ V}; I_D = 15 \text{ A}; T_j = 25 ^{\circ}\text{C};$ see <u>Figure 10</u>	-	9.8	11.3	mΩ
		$V_{GS} = 10 \text{ V; } I_D = 15 \text{ A; } T_j = 25 \text{ °C;}$ see <u>Figure 10</u>	-	7.55	8.65	mΩ
Dynamic char	acteristics					
Q_{GD}	gate-drain charge	V_{GS} = 4.5 V; I_D = 15 A; V_{DS} = 12.5 V; see <u>Figure 12</u> ; see <u>Figure 13</u>	-	1.2	-	nC
Q _{G(tot)}	total gate charge	V_{GS} = 4.5 V; I_D = 15 A; V_{DS} = 12.5 V; see Figure 12; see Figure 13	-	5.4	-	nC



2. Pinning information

Table 2. Pinning information



3. Ordering information

Table 3. Ordering information

Type number	Package		
	Name	Description	Version
PSMN9R0-25MLC	LFPAK33	Plastic single ended surface mounted package (LFPAK33); 4 leads	SOT1210

4. Limiting values

Table 4. Limiting values

In accordance with the Absolute Maximum Rating System (IEC 60134).

Symbol	Parameter	Conditions	Min	Max	Unit
V_{DS}	drain-source voltage	$T_j = 25$ °C	-	25	V
V_{GS}	gate-source voltage		-20	20	V
I _D	drain current	$V_{GS} = 10 \text{ V}; T_{mb} = 25 \text{ °C}; \text{ see } \frac{\text{Figure 1}}{\text{Model}}$	-	55	Α
		$V_{GS} = 10 \text{ V; } T_{mb} = 100 \text{ °C; see } Figure 1$	-	39	Α
I _{DM}	peak drain current	pulsed; $t_p \le 10 \mu s$; $T_{mb} = 25 \text{ °C}$; see Figure 4	-	219	Α
P _{tot}	total power dissipation	T _{mb} = 25 °C; see <u>Figure 2</u>	-	45	W
T _{stg}	storage temperature		-55	175	°C
Tj	junction temperature		-55	175	°C
T _{sld(M)}	peak soldering temperature		-	260	°C
V _{ESD}	electrostatic discharge voltage	MM (JEDEC JESD22-A115)	120	-	V
Source-drain of	diode				
Is	source current	T _{mb} = 25 °C	-	41	Α
I _{SM}	peak source current	pulsed; $t_p \le 10 \ \mu s$; $T_{mb} = 25 \ ^{\circ}C$	-	219	Α
Avalanche rug	gedness				
E _{DS(AL)S}	non-repetitive drain-source avalanche energy	V_{GS} = 10 V; $T_{j(init)}$ = 25 °C; I_D = 55 A; $V_{sup} \le$ 25 V; R_{GS} = 50 Ω; unclamped; see Figure 3	-	8.7	mJ

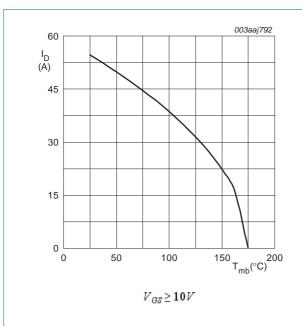


Fig 1. Continuous drain current as a function of mounting base temperature

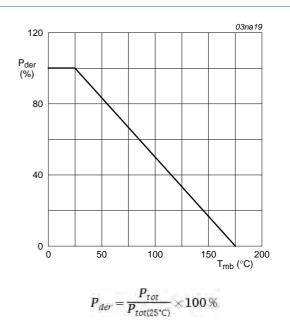


Fig 2. Normalized total power dissipation as a function of mounting base temperature

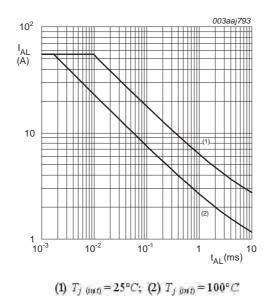
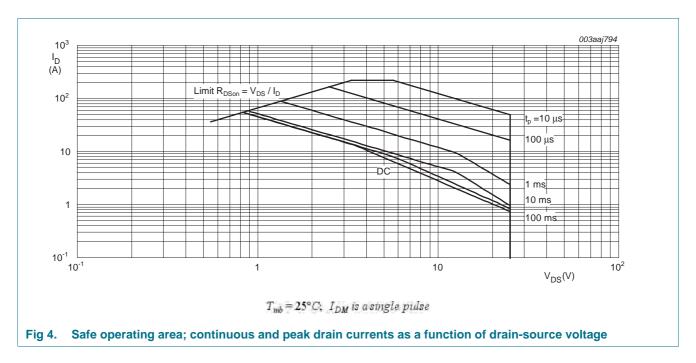


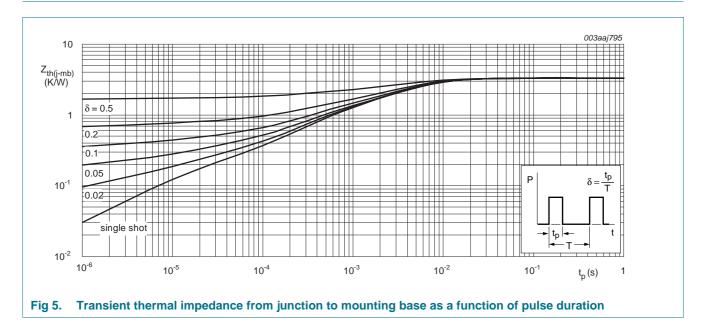
Fig 3. Single pulse avalanche rating; avalanche current as a function of avalanche time



5. Thermal characteristics

Table 5. Thermal characteristics

Symbol	Parameter	Conditions	Min	Тур	Max	Unit
$R_{th(j\text{-}mb)}$	thermal resistance from junction to mounting base	see <u>Figure 5</u>	-	3.1	3.32	K/W



6. Characteristics

Table 6 Characteristics

Table 6.	Characteristics					
Symbol	Parameter	Conditions	Min	Тур	Max	Unit
Static cha	racteristics					
V _{(BR)DSS}	drain-source	$I_D = 250 \mu A; V_{GS} = 0 V; T_j = 25 °C$	25	-	-	V
	breakdown voltage	$I_D = 250 \mu A; V_{GS} = 0 V; T_j = -55 °C$	22.5	-	-	V
$V_{GS(th)}$	gate-source threshold voltage	$I_D = 1 \text{ mA}; V_{DS} = V_{GS}; T_j = 25 \text{ °C}$	1.3	1.5	1.95	V
$\Delta V_{GS(th)}/\Delta^{-1}$	Γ gate-source threshold voltage variation with temperature		-	-3.5	-	mV/K
I _{DSS}	drain leakage current	$V_{DS} = 25 \text{ V}; V_{GS} = 0 \text{ V}; T_j = 25 \text{ °C}$	-	-	1	μΑ
		$V_{DS} = 25 \text{ V}; V_{GS} = 0 \text{ V}; T_j = 150 ^{\circ}\text{C}$	-	-	100	μΑ
I _{GSS}	gate leakage current	$V_{GS} = 16 \text{ V}; V_{DS} = 0 \text{ V}; T_j = 25 \text{ °C}$	-	-	100	nA
		$V_{GS} = -16 \text{ V}; V_{DS} = 0 \text{ V}; T_j = 25 \text{ °C}$	-	-	100	nA
R _{DSon}	drain-source on-state resistance	$V_{GS} = 4.5 \text{ V}; I_D = 15 \text{ A}; T_j = 25 ^{\circ}\text{C};$ see Figure 10	-	9.8	11.3	mΩ
		$V_{GS} = 4.5 \text{ V}; I_D = 15 \text{ A}; T_j = 150 ^{\circ}\text{C};$ see Figure 10; see Figure 11	-	-	18.1	mΩ
		$V_{GS} = 10 \text{ V}; I_D = 15 \text{ A}; T_j = 25 \text{ °C};$ see Figure 10	-	7.55	8.65	mΩ
		$V_{GS} = 10 \text{ V}$; $I_D = 15 \text{ A}$; $T_j = 150 \text{ °C}$; see Figure 10; see Figure 11	-	-	13.9	mΩ
R_{G}	gate resistance	f = 1 MHz	0.95	1.9	3.8	Ω
Dynamic o	characteristics					
Q _{G(tot)}	total gate charge	I_D = 15 A; V_{DS} = 12.5 V; V_{GS} = 10 V; see <u>Figure 12</u> ; see <u>Figure 13</u>	-	11.7	-	nC
		$I_D = 15 \text{ A}; V_{DS} = 12.5 \text{ V}; V_{GS} = 4.5 \text{ V};$ see <u>Figure 12</u> ; see <u>Figure 13</u>	-	5.4	-	nC
		$I_D = 0 \text{ A}; V_{DS} = 0 \text{ V}; V_{GS} = 10 \text{ V}$	-	11.1	-	nC
Q_{GS}	gate-source charge	$I_D = 15 \text{ A}$; $V_{DS} = 12.5 \text{ V}$; $V_{GS} = 4.5 \text{ V}$;	-	1.8	-	nC
Q _{GS(th)}	pre-threshold gate-source charge	see <u>Figure 12</u> ; see <u>Figure 13</u>	-	1.2	-	nC
Q _{GS(th-pl)}	post-threshold gate-source charge		-	0.6	-	nC
Q_{GD}	gate-drain charge		-	1.2	-	nC
$V_{GS(pl)}$	gate-source plateau voltage	I _D = 15 A; V _{DS} = 12.5 V; see <u>Figure 12</u> ; see <u>Figure 13</u>	-	2.5	-	V
C _{iss}	input capacitance	V _{DS} = 12.5 V; V _{GS} = 0 V; f = 1 MHz;	-	705	-	pF
C _{oss}	output capacitance	T _j = 25 °C; see <u>Figure 14</u>	-	206	-	pF
C _{rss}	reverse transfer capacitance		-	67	-	pF

 Table 6.
 Characteristics ...continued

Symbol	Parameter	Conditions	Min	Тур	Max	Unit
t _{d(on)}	turn-on delay time	$\begin{split} &V_{DS} = 12.5 \text{ V; } R_{L} = 0.8 \Omega; V_{GS} = 4.5 \text{ V;} \\ &R_{G(ext)} = 5 \Omega \end{split}$	-	7.1	-	ns
t _r	rise time		-	10.1	-	ns
t _{d(off)}	turn-off delay time		-	11.1	-	ns
t _f	fall time		-	6.1	-	ns
Q _{oss}	output charge	$V_{GS} = 0 \text{ V}; V_{DS} = 12.5 \text{ V}; f = 1 \text{ MHz};$ $T_j = 25 \text{ °C}$	-	5.3	-	nC
Source-drai	in diode					
V_{SD}	source-drain voltage	$I_S = 15 \text{ A}; V_{GS} = 0 \text{ V}; T_j = 25 ^{\circ}\text{C};$ see <u>Figure 15</u>	-	0.83	1.1	V
t _{rr}	reverse recovery time	$I_S = 15 \text{ A}$; $dI_S/dt = -100 \text{ A/}\mu\text{s}$; $V_{GS} = 0 \text{ V}$;	-	14.8	-	ns
Q _r	recovered charge	V _{DS} = 12.5 V	-	7.5	-	nC
t _a	reverse recovery rise time	$V_{GS} = 0 \text{ V; } I_S = 15 \text{ A; } dI_S/dt = -100 \text{ A/}\mu\text{s;}$ $V_{DS} = 12.5 \text{ V; see } \frac{\text{Figure } 16}{\text{Miss}}$	-	8.9	-	ns
t _b	reverse recovery fall time		-	5.9	-	ns

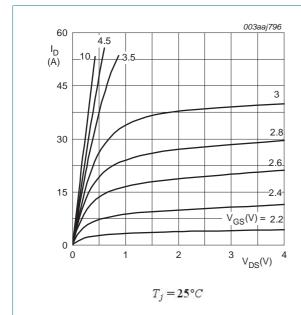


Fig 6. Output characteristics; drain current as a function of drain-source voltage; typical values

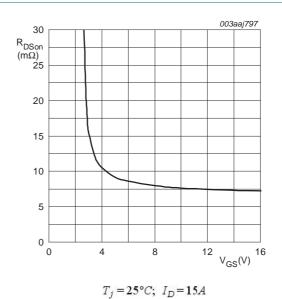


Fig 7. Drain-source on-state resistance as a function of gate-source voltage; typical values

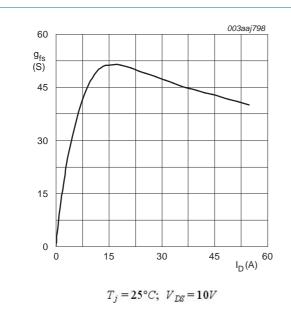


Fig 8. Forward transconductance as a function of drain current; typical values

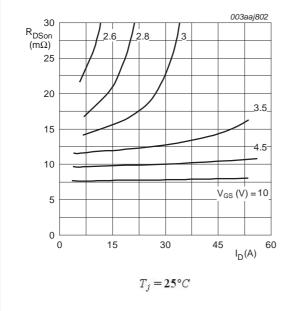


Fig 10. Drain-source on-state resistance as a function of drain current; typical values

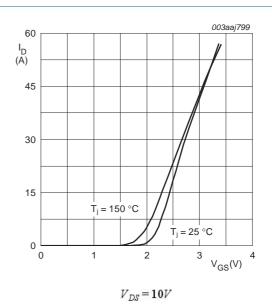


Fig 9. Transfer characteristics; drain current as a function of gate-source voltage; typical values

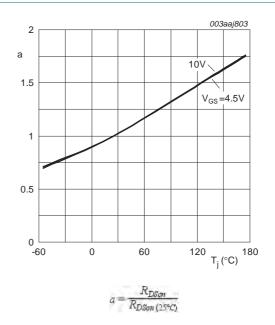


Fig 11. Normalized drain-source on-state resistance factor as a function of junction temperature

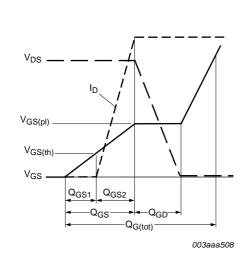


Fig 12. Gate charge waveform definitions

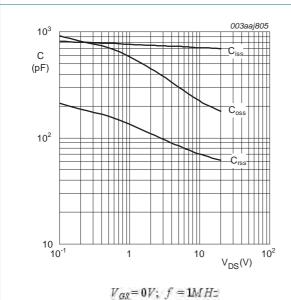
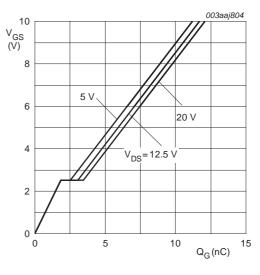


Fig 14. Input, output and reverse transfer capacitances as a function of drain-source voltage; typical values



 $T_j = 25^{\circ}C; I_D = 15A$

Fig 13. Gate-source voltage as a function of gate charge; typical values

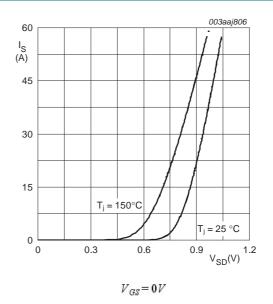
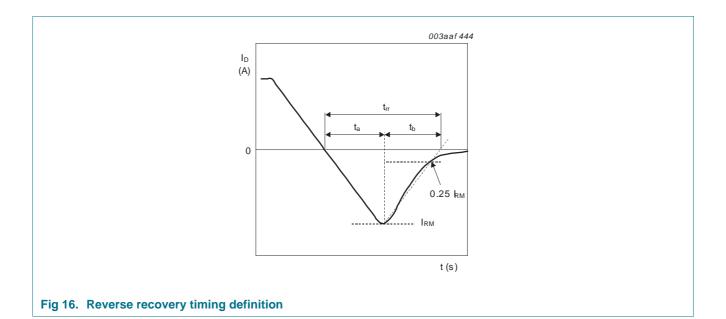


Fig 15. Source current as a function of source-drain voltage; typical values



7. Package outline

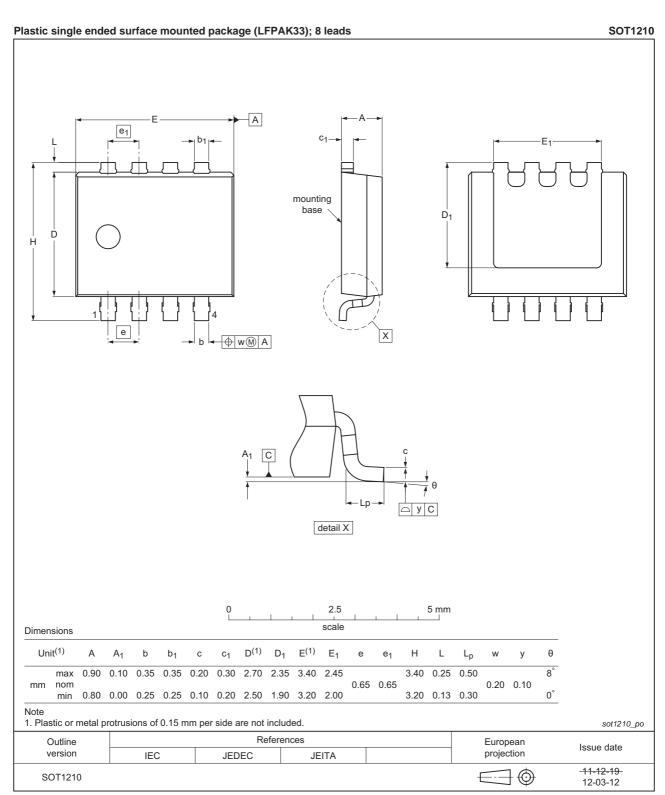


Fig 17. Package outline SOT1210 (LFPAK33)

PSMN9R0-25MLC

All information provided in this document is subject to legal disclaimers.

N-channel 25 V 8.65 mΩ logic level MOSFET in LFPAK33 using NextPower Technology

8. Revision history

Table 7. Revision history

Document ID	Release date	Data sheet status	Change notice	Supersedes	
PSMN9R0-25MLC v.3	20120615	Product data sheet	-	PSMN9R0-25MLC v.2	
Modifications:	 Various changes to 	content.			
PSMN9R0-25MLC v.2	20120607	Product data sheet	-	PSMN9R0-25MLC v.1	

N-channel 25 V 8.65 mΩ logic level MOSFET in LFPAK33 using NextPower Technology

9. Legal information

9.1 Data sheet status

Document status[1] [2]	Product status[3]	Definition
Objective [short] data sheet	Development	This document contains data from the objective specification for product development.
Preliminary [short] data sheet	Qualification	This document contains data from the preliminary specification.
Product [short] data sheet	Production	This document contains the product specification.

- [1] Please consult the most recently issued document before initiating or completing a design
- [2] The term 'short data sheet' is explained in section "Definitions".
- [3] The product status of device(s) described in this document may have changed since this document was published and may differ in case of multiple devices. The latest product status information is available on the Internet at URL http://www.nexperia.com.

9.2 Definitions

Preview — The document is a preview version only. The document is still subject to formal approval, which may result in modifications or additions. Nexperia does not give any representations or warranties as to the accuracy or completeness of information included herein and shall have no liability for the consequences of use of such information.

Draft — The document is a draft version only. The content is still under internal review and subject to formal approval, which may result in modifications or additions. Nexperia does not give any representations or warranties as to the accuracy or completeness of information included herein and shall have no liability for the consequences of use of such information.

Short data sheet — A short data sheet is an extract from a full data sheet with the same product type number(s) and title. A short data sheet is intended for quick reference only and should not be relied upon to contain detailed and full information. For detailed and full information see the relevant full data sheet, which is available on request via the local Nexperia sales office. In case of any inconsistency or conflict with the short data sheet, the full data sheet shall prevail.

Product specification — The information and data provided in a Product data sheet shall define the specification of the product as agreed between Nexperia and its customer, unless Nexperia and customer have explicitly agreed otherwise in writing. In no event however, shall an agreement be valid in which the Nexperia product is deemed to offer functions and qualities beyond those described in the Product data sheet

9.3 Disclaimers

Limited warranty and liability — Information in this document is believed to be accurate and reliable. However, Nexperia does not give any representations or warranties, expressed or implied, as to the accuracy or completeness of such information and shall have no liability for the consequences of use of such information. Nexperia takes no responsibility for the content in this document if provided by an information source outside of Nexperia.

In no event shall Nexperia be liable for any indirect, incidental, punitive, special or consequential damages (including - without limitation - lost profits, lost savings, business interruption, costs related to the removal or replacement of any products or rework charges) whether or not such damages are based on tort (including negligence), warranty, breach of contract or any other legal theory.

Notwithstanding any damages that customer might incur for any reason whatsoever, Nexperia's aggregate and cumulative liability towards customer for the products described herein shall be limited in accordance with the *Terms and conditions of commercial sale* of Nexperia.

Right to make changes — Nexperia reserves the right to make changes to information published in this document, including without limitation specifications and product descriptions, at any time and without notice. This document supersedes and replaces all information supplied prior to the publication hereof.

Suitability for use — Nexperia products are not designed, authorized or warranted to be suitable for use in life support, life-critical or safety-critical systems or equipment, nor in applications where failure or malfunction of a Nexperia product can reasonably be expected to result in personal injury, death or severe property or environmental damage. Nexperia and its suppliers accept no liability for inclusion and/or use of Nexperia products in such equipment or applications and therefore such inclusion and/or use is at the customer's own risk.

Quick reference data — The Quick reference data is an extract of the product data given in the Limiting values and Characteristics sections of this document, and as such is not complete, exhaustive or legally binding.

Applications — Applications that are described herein for any of these products are for illustrative purposes only. Nexperia makes no representation or warranty that such applications will be suitable for the specified use without further testing or modification.

Customers are responsible for the design and operation of their applications and products using Nexperia products, and Nexperia accepts no liability for any assistance with applications or customer product design. It is customer's sole responsibility to determine whether the Nexperia product is suitable and fit for the customer's applications and products planned, as well as for the planned application and use of customer's third party customer(s). Customers should provide appropriate design and operating safeguards to minimize the risks associated with their applications and products.

Nexperia does not accept any liability related to any default, damage, costs or problem which is based on any weakness or default in the customer's applications or products, or the application or use by customer's third party customer(s). Customer is responsible for doing all necessary testing for the customer's applications and products using Nexperia products in order to avoid a default of the applications and the products or of the application or use by customer's third party customer(s). Nexperia does not accept any liability in this respect.

Limiting values — Stress above one or more limiting values (as defined in the Absolute Maximum Ratings System of IEC 60134) will cause permanent damage to the device. Limiting values are stress ratings only and (proper) operation of the device at these or any other conditions above those given in the Recommended operating conditions section (if present) or the Characteristics sections of this document is not warranted. Constant or repeated exposure to limiting values will permanently and irreversibly affect the quality and reliability of the device.

PSMN9R0-25MLC

All information provided in this document is subject to legal disclaimers.

© Nexperia B.V. 2017. All rights reserved

N-channel 25 V 8.65 mΩ logic level MOSFET in LFPAK33 using NextPower Technology

Terms and conditions of commercial sale — Nexperia

products are sold subject to the general terms and conditions of commercial sale, as published at http://www.nexperia.com/profile/terms, unless otherwise agreed in a valid written individual agreement. In case an individual agreement is concluded only the terms and conditions of the respective agreement shall apply. Nexperia hereby expressly objects to applying the customer's general terms and conditions with regard to the purchase of Nexperia products by customer.

No offer to sell or license — Nothing in this document may be interpreted or construed as an offer to sell products that is open for acceptance or the grant, conveyance or implication of any license under any copyrights, patents or other industrial or intellectual property rights.

Export control — This document as well as the item(s) described herein may be subject to export control regulations. Export might require a prior authorization from competent authorities.

Non-automotive qualified products — Unless this data sheet expressly states that this specific Nexperia product is automotive qualified, the product is not suitable for automotive use. It is neither qualified nor tested in accordance with automotive testing or application requirements. Nexperia accepts no liability for inclusion and/or use of non-automotive qualified products in automotive equipment or applications.

In the event that customer uses the product for design-in and use in automotive applications to automotive specifications and standards, customer (a) shall use the product without Nexperia's warranty of the

product for such automotive applications, use and specifications, and (b) whenever customer uses the product for automotive applications beyond Nexperia's specifications such use shall be solely at customer's own risk, and (c) customer fully indemnifies Nexperia for any liability, damages or failed product claims resulting from customer design and use of the product for automotive applications beyond Nexperia's standard warranty and Nexperia's product specifications.

Translations — A non-English (translated) version of a document is for reference only. The English version shall prevail in case of any discrepancy between the translated and English versions.

9.4 Trademarks

Notice: All referenced brands, product names, service names and trademarks are the property of their respective owners.

10. Contact information

For more information, please visit:http://www.nexperia.com

For sales office addresses, please send an email to:salesaddresses@nexperia.com

Nexperia

PSMN9R0-25MLC

N-channel 25 V 8.65 mΩ logic level MOSFET in LFPAK33 using NextPower Technology

11. Contents

1	Product profile
1.1	General description
1.2	Features and benefits1
1.3	Applications
1.4	Quick reference data1
2	Pinning information
3	Ordering information2
4	Limiting values
5	Thermal characteristics4
6	Characteristics5
7	Package outline
8	Revision history11
9	Legal information12
9.1	Data sheet status
9.2	Definitions
9.3	Disclaimers
9.4	Trademarks13
10	Contact information 13